

ABSTRACT

An electrical package structure incorporating a chip with polymer thereon is described, including at least a package, a polymer and a molding compound. The package includes a carrier, at least one chip and multiple wires, wherein the chip is disposed on the carrier and the wires electrically connect the chip and the carrier. The polymer is disposed at the periphery of the chip possibly extending to the sidewalls of the chip and covering a portion of each wire near the chip, and the chip, the wires and the polymer are all enclosed in the molding compound. The polymer is preferably a stress buffer polymer like epoxy resin or polyimide, capable of inhibiting stress concentration at the periphery of the chip when the chip is subjected to repeated heat cycles for a long time. Therefore, the reliability of the electrical package structure can be improved.